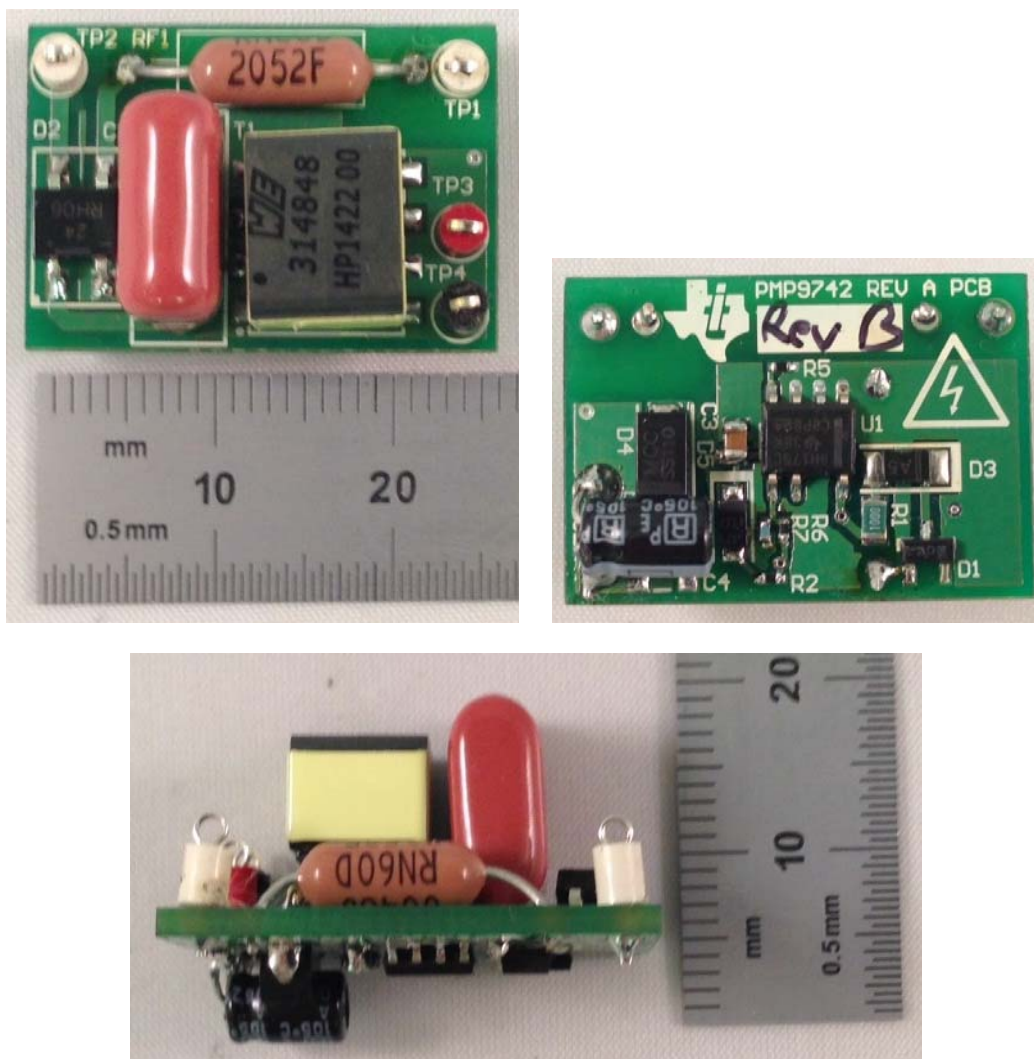
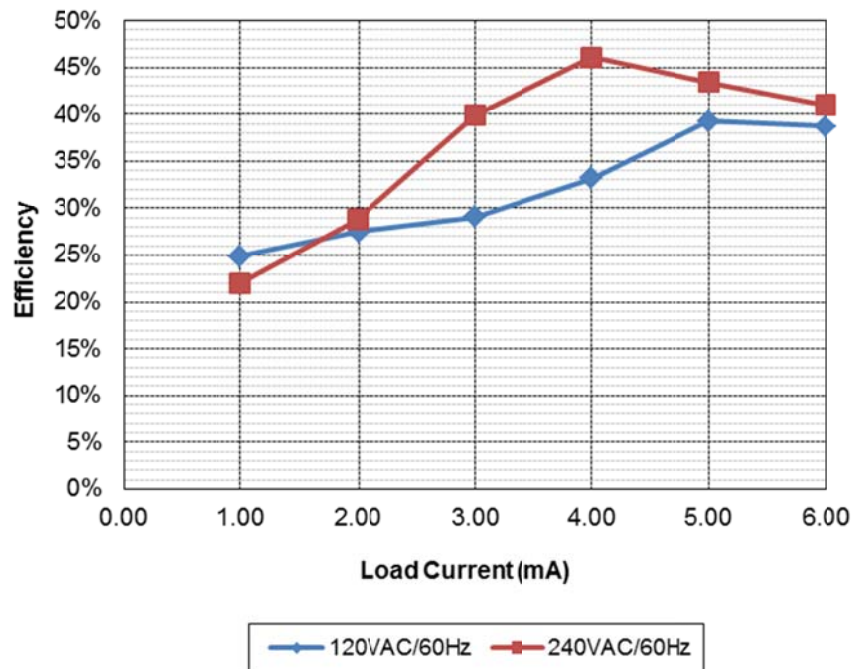


1 Photos

The photograph below shows the PMP9742 Rev B prototype assembly. This circuit was built on a PMP9742 Rev A PCB.



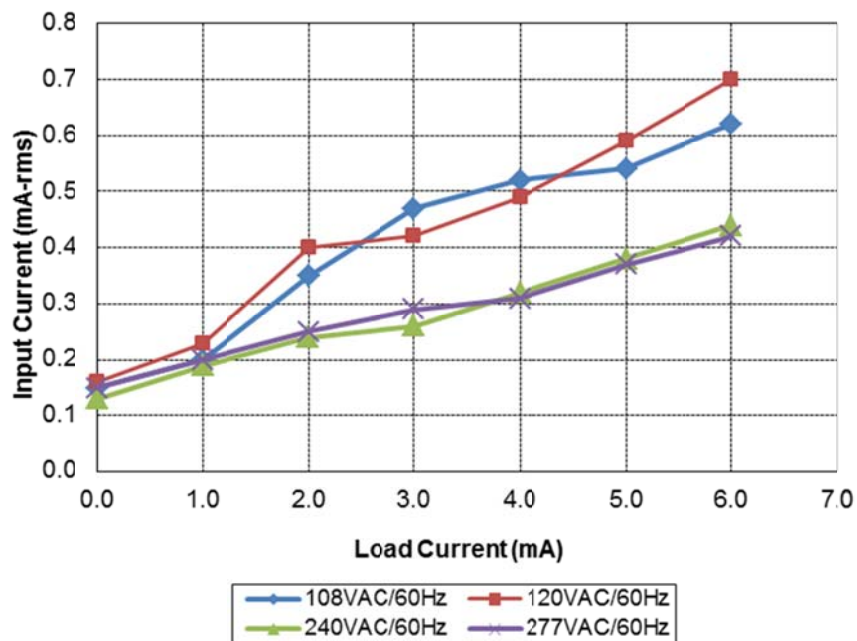
2 Efficiency



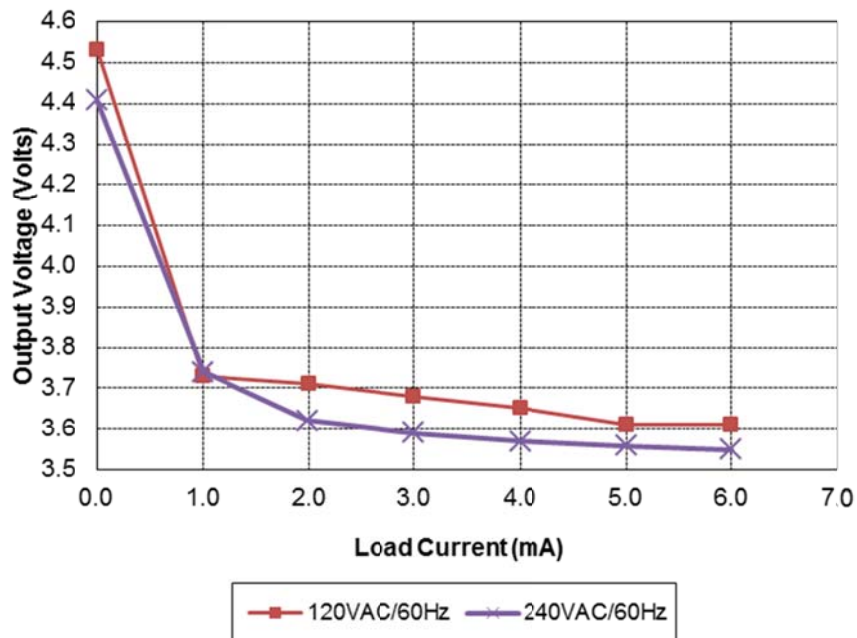
120VAC/60Hz								
I _{out} (mA)	V _{out}	V _{in}	I _{in} (mA _{rms})	P _{in} (mW)	PF	P _{out} (mW)	Losses (mW)	Efficiency
0.000	4.53	119.9	0.15	9		0.00	9	0.0%
1.00	3.73	119.9	0.20	15	0.56	3.73	11	24.9%
2.00	3.71	119.9	0.35	27	0.62	7.42	20	27.5%
3.00	3.68	119.9	0.47	38	0.68	11.04	27	29.1%
4.00	3.65	119.9	0.52	44	0.71	14.60	29	33.2%
5.00	3.61	119.9	0.54	46	0.73	18.05	28	39.2%
6.00	3.61	119.9	0.62	56	0.72	21.66	34	38.7%

240VAC/60Hz								
I _{out} (mA)	V _{out}	V _{in}	I _{in} (mA _{rms})	P _{in} (mW)	PF	P _{out} (mW)	Losses (mW)	Efficiency
0.000	4.41	239.7	0.13	4		0.00	4	0.0%
1.00	3.74	239.7	0.19	17	0.34	3.74	13	22.0%
1.99	3.62	239.7	0.24	25	0.46	7.20	18	28.8%
3.00	3.59	239.7	0.26	27	0.43	10.77	16	39.9%
4.00	3.57	239.7	0.32	31	0.40	14.28	17	46.1%
5.00	3.56	239.7	0.38	41	0.46	17.80	23	43.4%
6.00	3.55	239.7	0.44	52	0.51	21.30	31	41.0%

3 Input Current



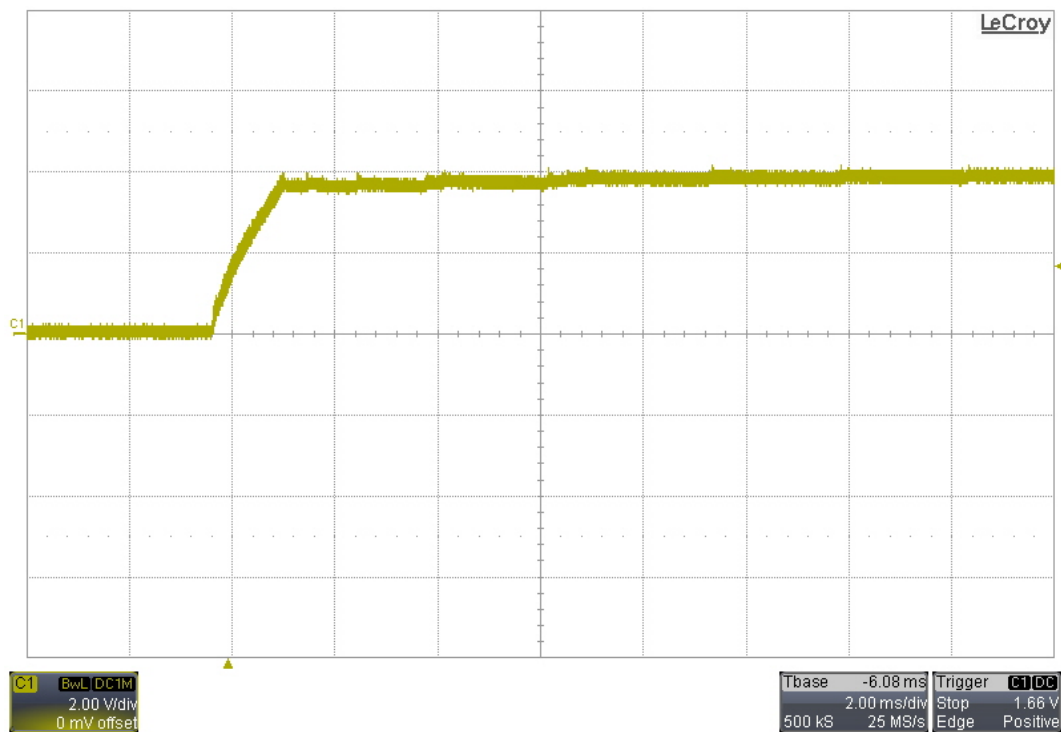
4 Load Regulation



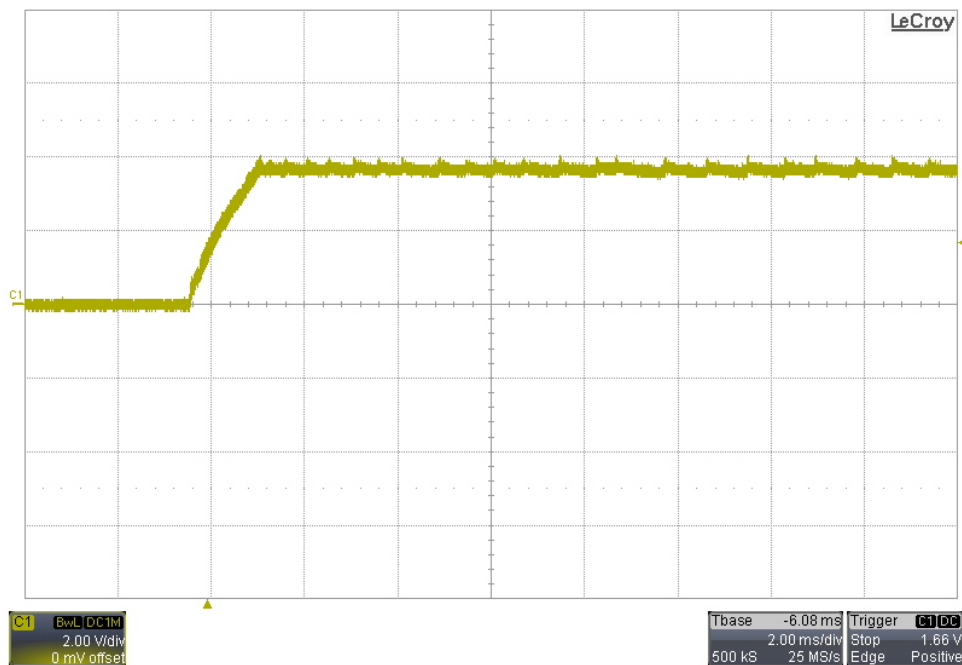
5 Startup

Channel 1 shows the AC input voltage. Channel 2 shows the output voltage.

5.1 120VAC/60Hz Startup – 0A Load



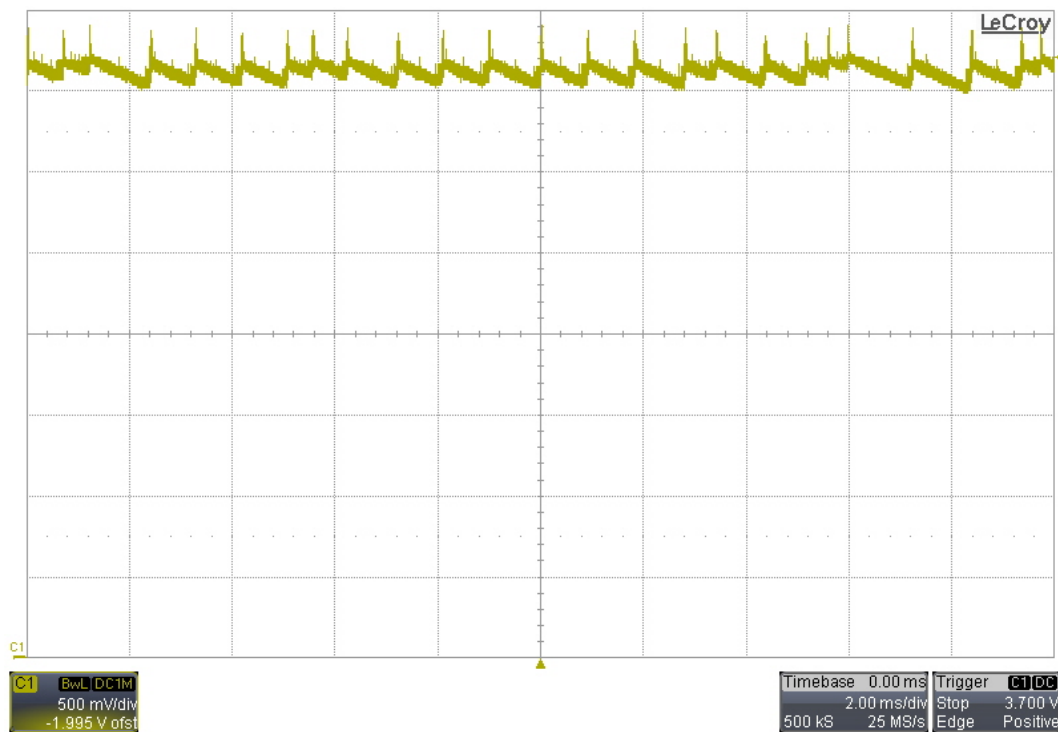
5.2 240VAC/60Hz Startup – 600Ω Load



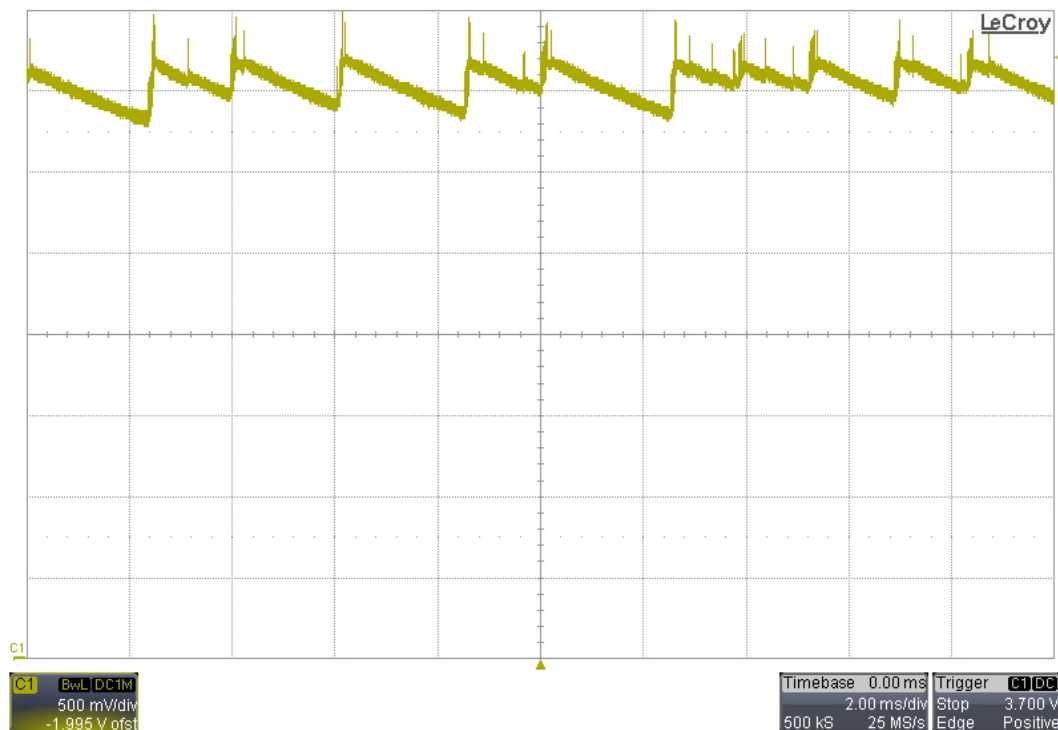
6 Output Ripple Voltage

The output was loaded with 5mA.

6.1 108VAC/60Hz Output Ripple Voltage



6.2 277VAC/60Hz Output Ripple Voltage

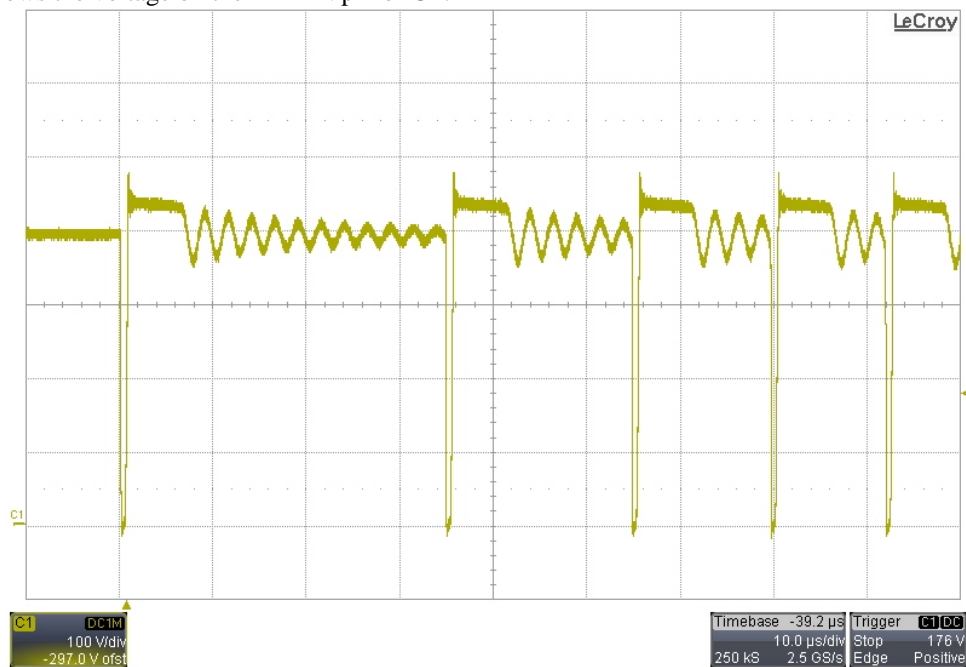


7 Switching Waveforms

The images below show the voltage waveforms on the switching devices within the supply. The input was 277VAC/60Hz. The output was loaded 5mA.

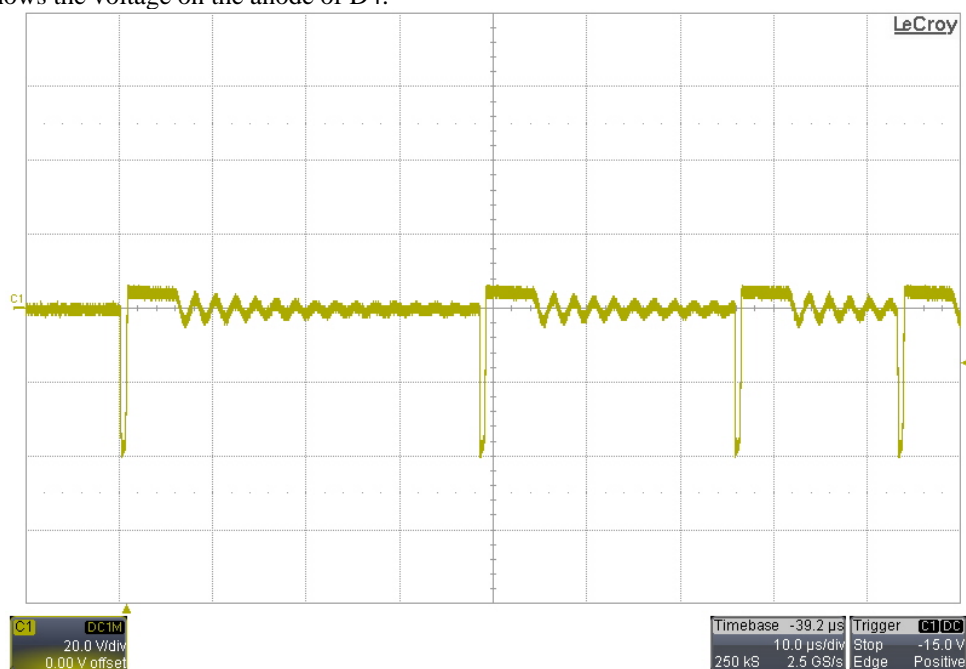
7.1 Primary Waveforms

The image below shows the voltage on the DRAIN pin of U1.



7.2 Secondary Waveforms

The image below shows the voltage on the anode of D4.



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